



QLPD04DXNB
(PHOTO DIODE)



Product Outline:

QLPD04DXNB is a Photodiode LED. 5.2x4.4mm lens type with Black resin (side detecting). This Photo Diode pairs well with QLIR01DXGCD or QLIR01DXGCD1 (5mm IR emitter).

Features:

- With Black resin
- 70° Viewing angle ($\pm 10^\circ$)
- RoHS compliant
- Custom Bin available upon special request

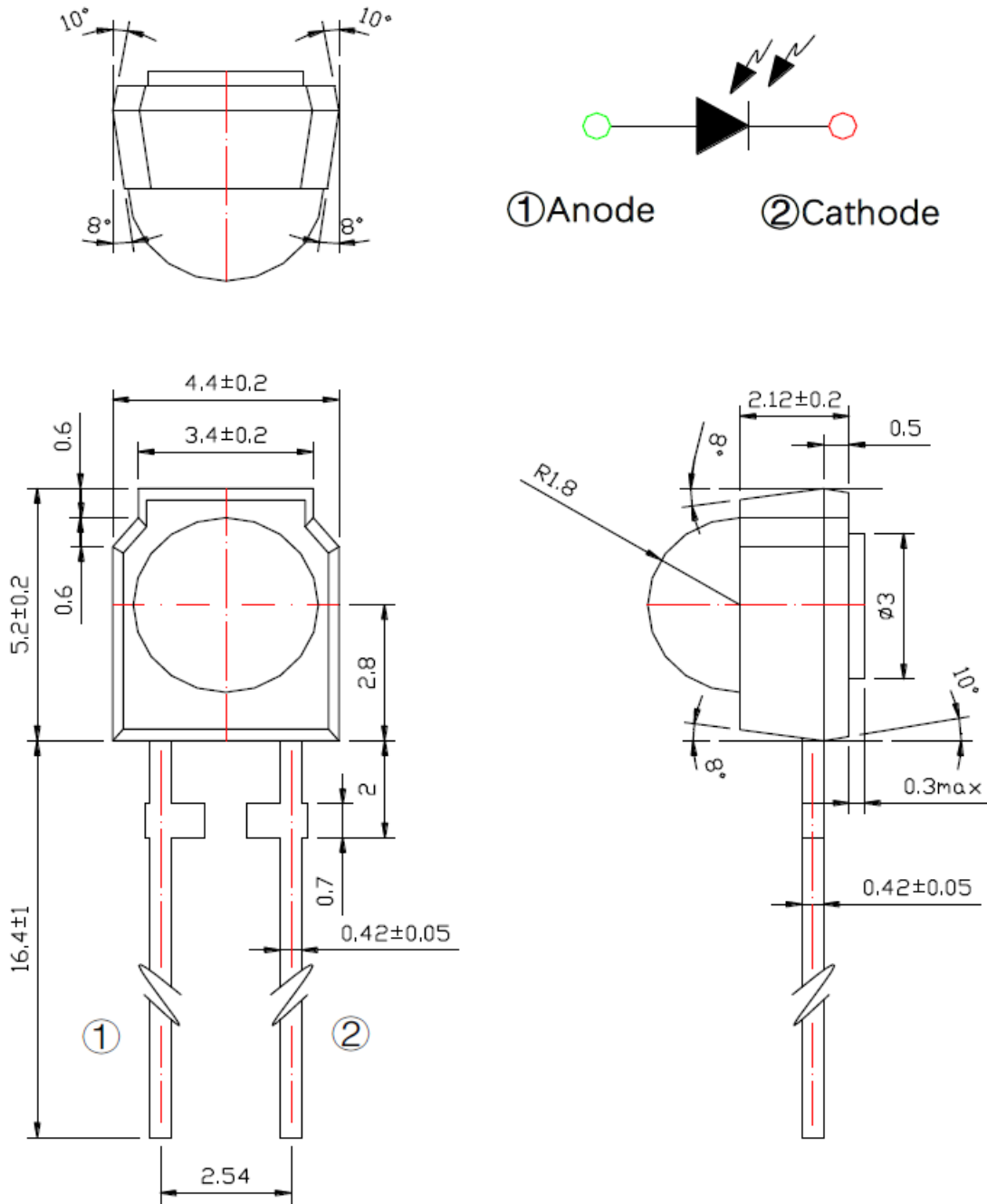
Application:

- Access Control & Security
- Home & Building Automation
- Appliances & Tools
- Light curtainetc
- Smoke detector

Compliance and Certification:



■ **Mechanical Property:**
(Dimension)



SIGN: 1. Anode
2. Cathode

Tolerance is ± 0.25 mm unless otherwise specified



■ ELEMENT APPEARANCE

Model No.	Material	Lighting Color	Resin Color
QLPD04DXNB	AlGaAs/ GaAs	Non-Visible	Black

■ ABSOLUTE MAXIMUM RATINGS AT Ta=25°C

Characteristic	Symbol	Rating	Unit
Operating temperature	T _{opr}	-40 to +85	°C
Storage temperature	T _{stg}	-25 to +85	°C
Solder Temperature	T _{sol}	245 for 5sec	°C
Reverse Breakdown Voltage	VBR	35	V

■ ELECTRO-OPTICAL CHARACTERISTICS AT Ta=25°C

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
Open Circuit Voltage	V _{oc}	E _e = 1mW/cm ² λ p= 940 nm		0.40		V
Short – Circuit Current	I _{sc}	E _e = 1mW/cm ² λ p= 940 nm		25		μA
Total capacitance	C _t	V _r = 5V, f = 1Mhz, E _e = 0mW/cm ²		18		pF
Reverse Light current	I _L	E _e = 1.0 Mw/cm ² λ p= 940 nm V _R =5V	25	35		μA
Rise Time	T _r	V _r =5V, R _L = 1000Ω		10		ns
Fall Time	T _f	V _r =5V, R _L = 1000Ω		10		ns
Dark Current	I _d	E _e = 0mW/cm ² V _R =5V			30	nA
Wavelength of the max. sensitivity	λ p		840		980	nm
Viewing angle	2θ 1/2			70		Deg

*Radiant Intensity Measurement allowance is ±15%

** Forward voltage Measurement allowance is ±0.05V

*** Peak emission wavelength Measurement allowance is ±1nm



Reverse light current bin (L):

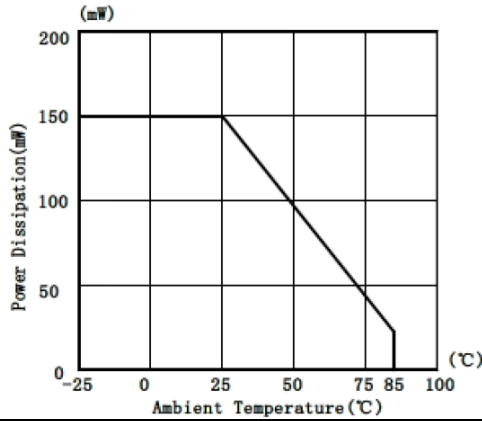
Ee=1.0mW/cm2 (mA)			
Unit	Bin Code name	Min.	Max.
μA	Bin 1	25.0	37.5
	Bin 2	37.6	50.0

Measurement tolerance is +/- 15%

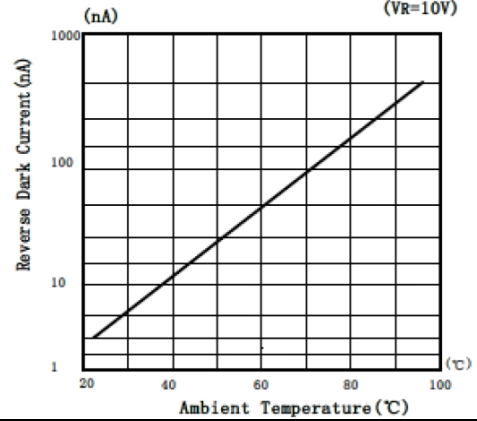


■ Characteristic Curves

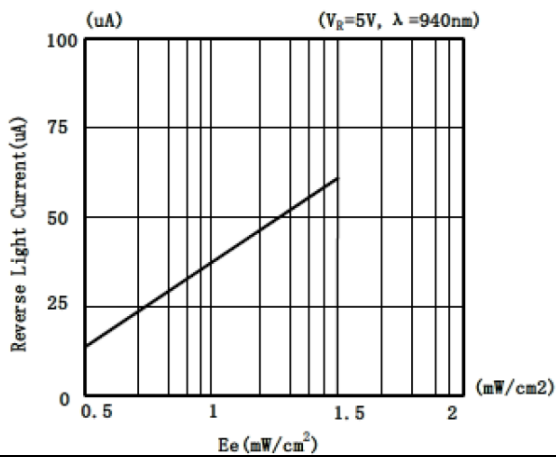
Power Dissipation vs. Ambient Temperature



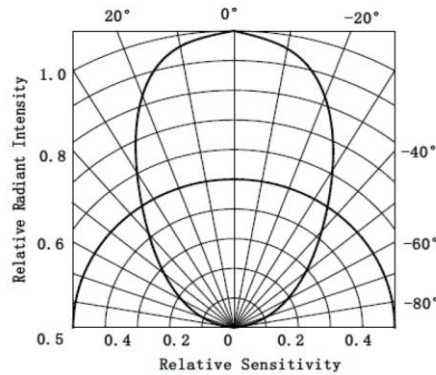
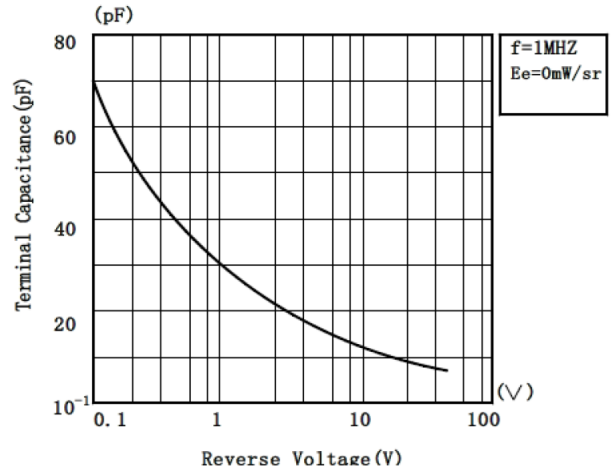
Dark Current vs. Ambient Temperature (VR=10V)



Reverse Light Current vs. Ee



Terminal Capacitance vs. Reverse Voltage





■ **Reliability test:**

No	Item	Condition	Time/Cycle	Criteria	Ac / Re	Sample size
1	Soldering Heat Test	260°C	5 sec	Open / Short	0 / 1	60 pcs
2	Thermal Shock	0 (5min) °C ~100 (5min) °C	20 cycle	Open / Short	0 / 1	60 pcs
3	High Temp. Storage	100°C	1000 Hrs	Open / Short	0 / 1	60 pcs
4	Low Temp. Storage	-40°C	1000 Hrs	Open / Short	0 / 1	60 pcs
5	Temperature Cycle Test	-40 ~85 °C	100 Cycles , 200Hrs	Open / Short	0 / 1	60 pcs
6	High Temp. High Humidity Test	60 , 90% RH °C	1000 Hrs	Open / Short	0 / 1	60 pcs
7	DC Operation Life Test	IF=100mA	1000 Hrs	Power decay	≤ 30%	60 pcs



■ APPLICATION NOTES :

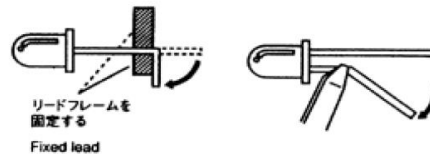
Static Electricity and Surge

Static electricity and surge damage LEDs. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs. All devices, equipment and machinery must be electrically grounded.

Lead Forming

The leads should be bent at a point at least 3mm from the epoxy resin of the LEDs.

Bending should be performed with the base firmly fixed by means of a jig or radio pliers.



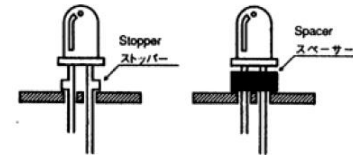
Mounting Method

The leads should be formed so they are aligned exactly with the holes on the PC board.

This will eliminate any stress on the LEDs.

Use LEDs with stoppers or resin spacer to accurately position the LEDs.

The epoxy resin base should not be touching the PC board when mounting the LEDs.



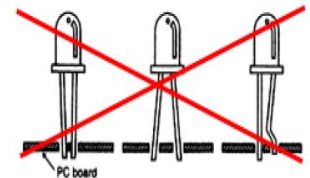
Mechanical stress to the resin may be caused by the warping of the PC board when soldering.

The LEDs must not be designed into a product or system where the epoxy lens is

pressed into a plastic or metal board. The lens part of the LED

must not be glued onto plastic or metal. The mechanical stress

to the lead-frame must be minimized.



Soldering

Solder the LEDs no closer than 3mm from the base of the epoxy resin.

For solder dipping, it may be necessary to fix the LEDs for correct positioning.

When doing this, any mechanical stress to the LEDs must be avoided.

When soldering, do not apply any mechanical force to the leadframe while heating.

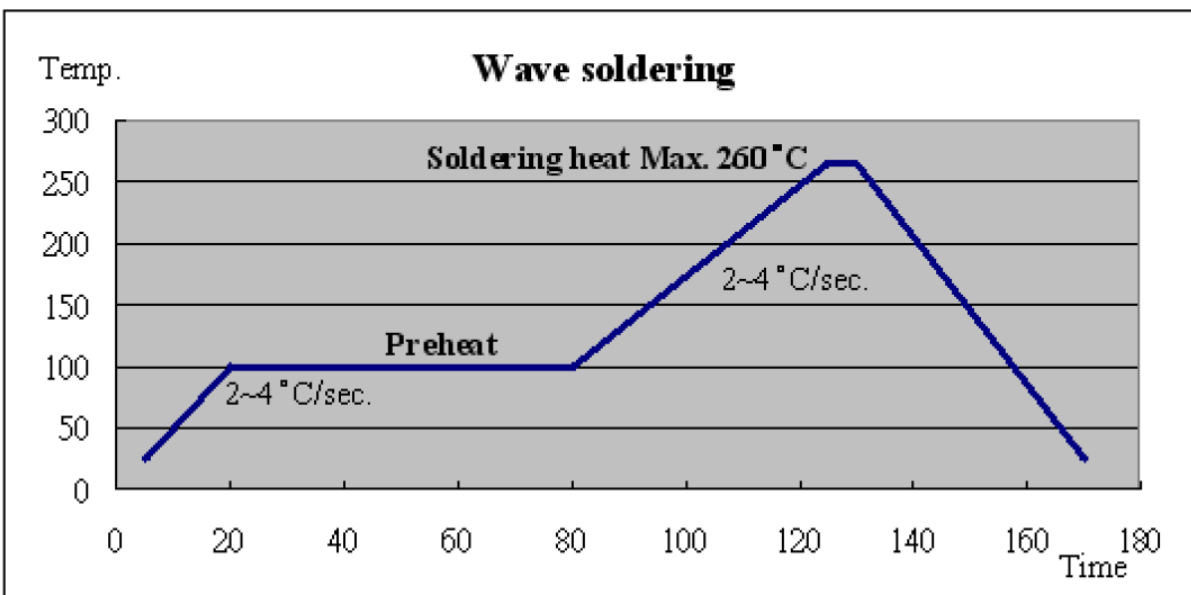
Repositioning after soldering must be avoided.



■ Solder Profile:

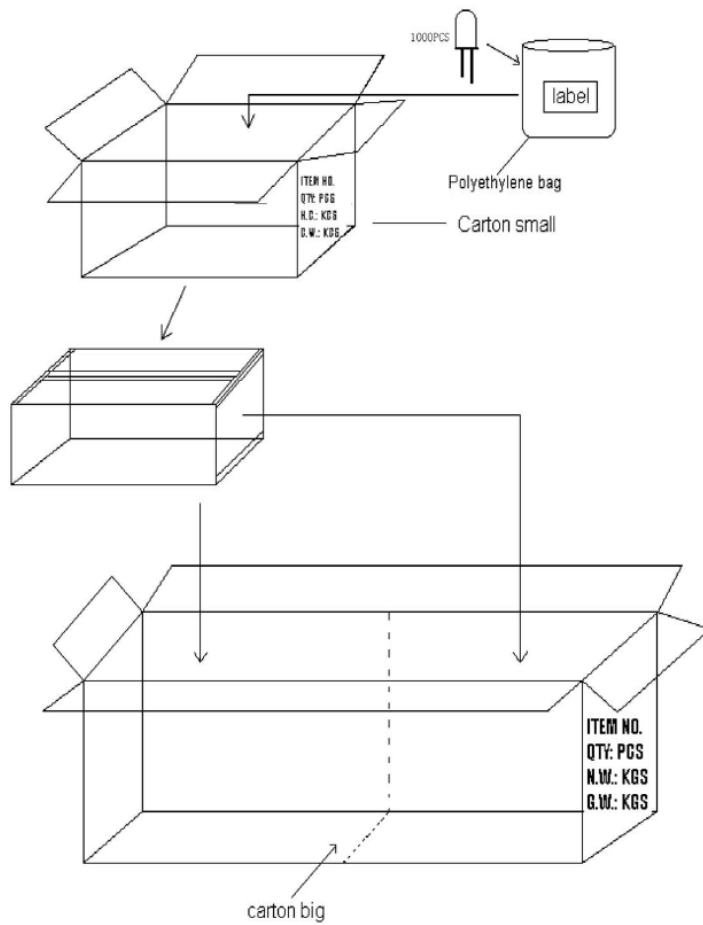
-The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

Shape	Lead Frame Type / Holder Type
Hand soldering	1.Temp.at tip of iron : 300 °C MAX. 2.Soldering time : 3 sec MAX. 3.Distance : 3 mm MIN (from solder joint to case)
DIP soldering	1.Preheat temp : 100 °C MAX , 60 sec MAX. 2.Bath temp : 260 °C MAX. 3.Bath time : 5 sec MAX. 4.Distance : 3 mm MIN (From solder joint to case).
Reflow soldering	NO
Shape	SMD Type
Hand soldering	1.Temp.at tip of iron : 300 °C MAX. 2.Soldering time : 3 sec MAX.
DIP soldering	1.Preheat temp. : 120-150 °C , 60-120 sec. 2.Bath temp. : 260 °C MAX. 3.Bath time : 5 sec
Reflow soldering	1.Preheat temp. : 150-180 °C , 120 sec MAX. 2.Peak temp. : 260 °C MAX. 3.Peak time : 10 sec MAX.





■ Taping & Packing:


The boxes are not water resistant and they must be kept away from water and moisture. The LEDs are packed in cardboard boxes after packaging in normal or anti-electrostatic bags. Cardboard boxes will be used to protect the LEDs from mechanical shocks during transportation.




Labeling


Quantity: XXXX




Quelighting P/N: XXXXXX


Lot number: XXXXX

lv Bin: XX

Color Bin: XX

Vf Bin: XX

Date Code: XXXX

Ordering Information:

Part #	Multiple Quantities	Quantity per bag
QLPD04DXNB		1000pcs



Revision History:

Revision Date:	Changes:	Version #:
10-08-2023	Initial release	1.0

